MASER
ENGINEERING

DECAPSULATION SERVICES

- LASER ABLATION DECAPSULATION
- WET CHEMICAL DECAPSULATION
- MICROWAVE INDUCED PLASMA DECAPSULATION (MIP)
- MECHANICAL DECAPSULATION
- LED LENS REMOVAL
- HIGH PIN COUNT PACKAGE DECAPSULATION

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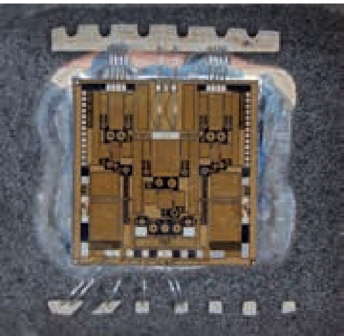
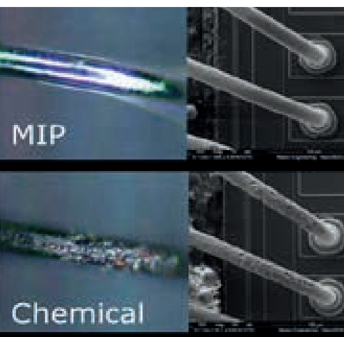


LASER DECAPSULATION

- Laser assisted decapsulation to minimize the amount of chemicals needed for package decapsulation
- Exposure of bond wires /wedge bonds without the use of any chemicals
- Laser marking ability for different materials
- Ability to cut glass and remove glass covers of sensors
- Selective area decapsulation

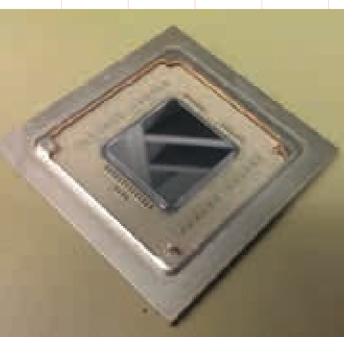
WET CHEMICAL DECAPSULATION

- Plastic package decapsulation of Cu, Au and Al wired packages
- Polyimide layer removal of semiconductor products
- Decapsulation of devices soldered to a PCB
- RDL removal from WLCSP devices
- Complete package removal keeping the die and bond wires intact
- GaAs die decapsulation



MICROWAVE INDUCED PLASMA DECAPSULATION (MIP)

- Plasma decapsulation of copper bond wire packages
- No passivation layer / die damage due to the decapsulation process
- Cu protecting Palladium Coating unharmed
- Effective decapsulation method for harsh environment tested samples
- EOS damage unharmed after decapsulation
- Completely chemical free decapsulation process
- Silicone LED lens removal



MECHANICAL DECAPSULATION

- Automated Selected Area Polishing tool (ASAP-1)
- De-lidding of ceramic samples
- Back-side QFN sample preparation keeping the down bonds intact
- Mechanical opening of round TO-xx devices
- Through PCB sample preparation for back-side Failure Localization
- Stacked die removal

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